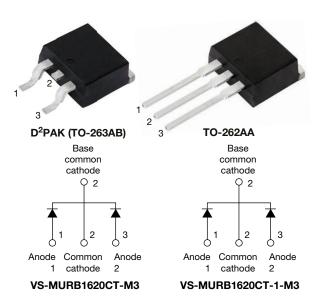
VS-MURB1620CT-M3, VS-MURB1620CT-1-M3

www.vishay.com

Vishay Semiconductors

Ultrafast Rectifier, 2 x 8 A FRED Pt®



LINKS TO ADDITIONAL RESOURCES



PRIMARY CHARACTERISTICS							
I _{F(AV)}	2 x 8 A						
V _R	200 V						
V _F at I _F	0.895 V						
t _{rr}	35 ns						
T _J max.	175 °C						
Package	D ² PAK (TO-263AB), TO-262AA						
Circuit configuration	Common cathode						

FEATURES

- Ultrafast recovery time
- Low forward voltage drop
- · Low leakage current
- 175 °C operating junction temperature



- Meets MSL level 1, per J-STD-020, LF maximum peak of 245 °C
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

DESCRIPTION / APPLICATIONS

MUR.. series are the state of the art ultrafast recovery rectifiers specifically designed with optimized performance of forward voltage drop and ultrafast recovery time.

The planar structure and the platinum doped life time control, guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in the output rectification stage of SMPS, UPS, DC/DC converters as well as freewheeling diode in low voltage inverters and chopper motor drives.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

MECHANICAL DATA

Case: D²PAK (TO-263AB), TO-262AA

Molding compound meets UL 94 V-0 flammability rating

Terminals: matte tin plated leads, solderable per J-STD-002

ABSOLUTE MAXIMUM RA	ATINGS				
PARAMETER		SYMBOL	TEST CONDITIONS	MAX.	UNITS
Peak repetitive reverse voltage		V_{RRM}		200	V
Average rectified forward current	per leg	ı		8.0	
Average rectified forward current	total device	I _{F(AV)}	Rated V _R , T _C = 150 °C	16	^
Non-repetitive peak surge current per leg		I _{FSM}		100	A
Peak repetitive forward current per I	eg	I_{FM}	Rated V _R , square wave, 20 kHz, T _C = 150 °C	16	
Operating junction and storage temp	peratures	T _J , T _{Stg}		-65 to +175	°C

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Breakdown voltage, blocking voltage	V_{BR} , V_{R}	I _R = 100 μA	200	-	-		
Forward voltage	V	I _F = 8 A	-	-	0.975	V	
Forward voltage	V _F	I _F = 8 A, T _J = 150 °C	-	-	0.895		
Reverse leakage current		$V_R = V_R$ rated	-	-	5		
neverse leakage current	I _R	$T_J = 150 ^{\circ}\text{C}, V_R = V_R \text{rated}$	-	-	250	μA	
Junction capacitance	C _T	V _R = 200 V	-	25	-	pF	
Series inductance	L _S	Measured lead to lead 5 mm from package body	-	8.0	-	nH	

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DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CO	NDITIONS	MIN.	TYP.	MAX.	UNITS	
Reverse recovery time		$I_F = 1.0 \text{ A}, dI_F/dt =$	50 A/μs, V _R = 30 V	-	-	35		
	t _{rr}	$I_F = 0.5 \text{ A}, I_R = 1.0$	-	-	25			
		T _J = 25 °C	I _F = 8 A	-	20	-	A nC	
		T _J = 125 °C		-	34	-		
Dook room ourrent	I _{RRM}	T _J = 25 °C		-	1.7	-		
Peak recovery current		T _J = 125 °C	$dI_F/dt = 200 A/\mu s$ $V_B = 160 V$	-	4.2	-		
Poverse resource charge	0	T _J = 25 °C	*H = 100 *	-	23	-		
Reverse recovery charge	Q _{rr}	T _J = 125 °C		=	75	-	110	

THERMAL - MECHANICAL SPECIFICATIONS							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Maximum junction and storage temperature range	T _J , T _{Stg}		-65	-	175	°C	
Thermal resistance, junction-to-case per leg	R _{thJC}		-	-	3.0		
Thermal resistance, junction-to-ambient per leg	R _{thJA}		-	-	50	°C/W	
Thermal resistance, case-to-heatsink	R _{thCS}	Mounting surface, flat, smooth, and greased	-	0.5	-		
Weight			-	2.0	-	g	
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)	
		Case style D ² PAK (TO-263AB)		MURE	1620CT	•	
Marking device		Case style TO-262		MURB1620CT-1			

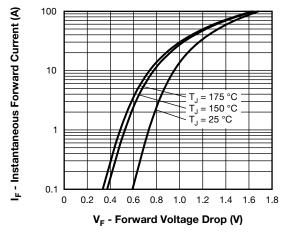


Fig. 1 - Typical Forward Voltage Drop Characteristics

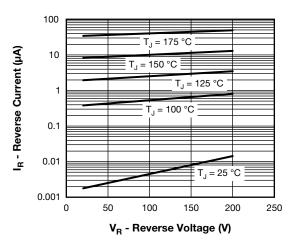


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

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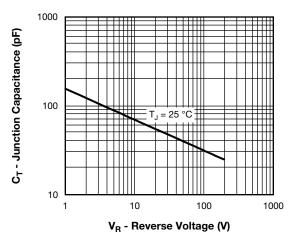


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

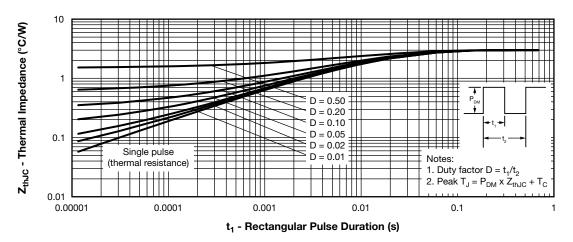


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

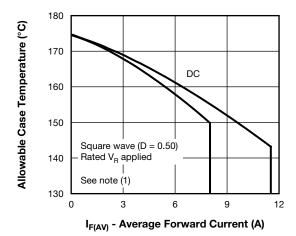


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

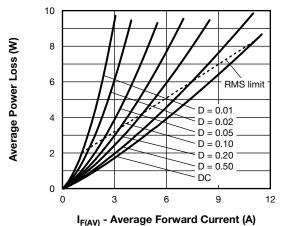


Fig. 6 - Forward Power Loss Characteristics

Note

 $\begin{array}{ll} \text{(1)} & \text{Formula used: } T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}; \\ Pd = \text{forward power loss} = I_{F(AV)} \times V_{FM} \text{ at } (I_{F(AV)}/D) \text{ (see fig. 6)}; \\ Pd_{REV} = \text{inverse power loss} = V_{R1} \times I_R \text{ (1 - D)}; I_R \text{ at } V_{R1} = \text{rated } V_R \\ \end{array}$

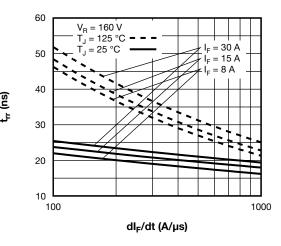


Fig. 7 - Typical Reverse Recovery Time vs. dl_F/dt

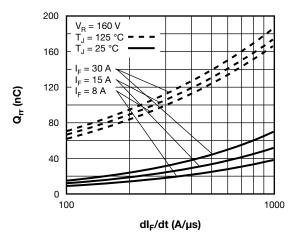
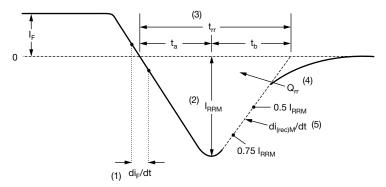


Fig. 8 - Typical Stored Charge vs. dl_F/dt



- (1) di_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) t_{rr} reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through 0.75 I_{RBM} and 0.50 I_{RBM} extrapolated to zero current.
- (4) Q_{rr} area under curve defined by t_{rr} and I_{RRM}

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(5) $di_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

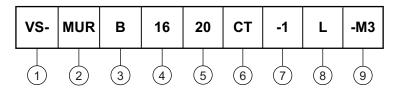
Fig. 9 - Reverse Recovery Waveform and Definitions

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ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

Ultrafast MUR series

- Current rating (16 = 16 A)

5 - Voltage rating (20 = 200 V)

6 - CT = center tap (dual)

7 • None = D²PAK (TO-263AB)

• -1 = TO-262AA

8 - • None = tube (50 pieces)

• L = tape and reel (left oriented, for D²PAK (TO-263AB) package)

• R = tape and reel (right oriented, for D²PAK (TO-263AB) package)

9 - Environmental digit:

-M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

ORDERING INFORMATION (Example)						
PREFERRED P/N	BASE QUANTITY	PACKAGING DESCRIPTION				
VS-MURB1620CTL-M3	800	13" diameter plastic tape and reel				
VS-MURB1620CT-M3	50	Antistatic plastic tubes				
VS-MURB1620CTR-M3	800	13" diameter plastic tape and reel				
VS-MURB1620CT-1-M3	50	Antistatic plastic tubes				

LINKS TO RELATED DOCUMENTS	3	
	D ² PAK (TO-263AB)	www.vishav.com/doc?96164
Dimensions —	TO-262AA	www.vishay.com/doc?96165
Dest seeding information	D ² PAK (TO-263AB)	www.vishay.com/doc?95444
Part marking information —	TO-262AA	www.vishay.com/doc?95443
Packaging information	D ² PAK (TO-263AB)	www.vishay.com/doc?96424
SPICE model		www.vishav.com/doc?96995



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D²PAK

DIMENSIONS in millimeters and inches



SYMBOL	MILLIM	ETERS	INC	HES	NOTES		SYMBOL	MILLIM	ETERS	INC	HES	NOTES
STWIBOL	MIN.	MAX.	MIN.	MAX.	NOTES	NOTES	STWBOL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.06	4.83	0.160	0.190			D1	6.86	8.00	0.270	0.315	3
A1	0.00	0.254	0.000	0.010			Е	9.65	10.67	0.380	0.420	2, 3
b	0.51	0.99	0.020	0.039			E1	7.90	8.80	0.311	0.346	3
b1	0.51	0.89	0.020	0.035	4		е	2.54	BSC	0.100	BSC	
b2	1.14	1.78	0.045	0.070			Н	14.61	15.88	0.575	0.625	
b3	1.14	1.73	0.045	0.068	4		L	1.78	2.79	0.070	0.110	
С	0.38	0.74	0.015	0.029			L1	-	1.65	-	0.066	3
c1	0.38	0.58	0.015	0.023	4		L2	1.27	1.78	0.050	0.070	
c2	1.14	1.65	0.045	0.065			L3	0.25	BSC	0.010	BSC	
D	8.51	9.65	0.335	0.380	2		L4	4.78	5.28	0.188	0.208	

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inches
- (7) Outline conforms to JEDEC® outline TO-263AB

Revision: 13-Jul-17 Document Number: 96164



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TO-262AA

DIMENSIONS in millimeters and inches

Modified JEDEC® outline TO-262







⊕ 0.010 **M** A**M** B

Lead assignments



Diodes 1. - Anode (two die)/open (one die)

2., 4. - Cathode

3. - Anode



Section B - B and C - C Scale: None

SYMBOL	MILLIMETERS		INC	HES	NOTES				
OTMIDOL	MIN.	MAX.	MIN.	MAX.	NOTES				
Α	4.06	4.83	0.160	0.190					
A1	2.03	3.02	0.080	0.119					
b	0.51	0.99	0.020	0.039					
b1	0.51	0.89	0.020	0.035	4				
b2	1.14	1.78	0.045	0.070					
b3	1.14	1.73	0.045	0.068	4				
С	0.38	0.74	0.015	0.029					
c1	0.38	0.58	0.015	0.023	4				
c2	1.14	1.65	0.045	0.065					
D	8.51	9.65	0.335	0.380	2				
D1	6.86	8.00	0.270	0.315	3				
Е	9.65	10.67	0.380	0.420	2, 3				
E1	7.90	8.80	0.311	0.346	3				
е	2.54	BSC	0.100) BSC					
L	13.46	14.10	0.530	0.555					
L1	-	1.65	-	0.065	3				
L2	3.56	3.71	0.140	0.146					

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
 (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- Controlling dimension: inches
- Outline conform to JEDEC® TO-262 except A1 (max.), b (min., max.), b1 (min.), b2 (max.), c (min.), c1(min.), c2 (max.), D (min.), E (max.), L1 (max.), L2 (min., max.)



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